

Schottky Rectifier, 3.5 A


D-PAK (TO-252AA)


FEATURES

- Popular D-PAK outline
- Small foot print, surface mountable
- Low forward voltage drop
- High frequency operation
- Guard ring for enhanced ruggedness and long term reliability
- Compliant to RoHS Directive 2002/95/EC
- Meets MSL level 1, per J-STD-020, LF maximum peak of 260 °C



PRODUCT SUMMARY	
Package	D-PAK (TO-252AA)
$I_{F(AV)}$	3.5 A
V_R	100 V
V_F at I_F	See Electrical table
I_{RM}	4.9 mA at 125 °C
T_J max.	150 °C
Diode variation	Single die
E_{AS}	5 mJ

DESCRIPTION

The VS-30WQ10FNPbF surface mount Schottky rectifier has been designed for applications requiring low forward drop and small foot prints on PC board. Typical applications are in disk drives, switching power supplies, converters, freewheeling diodes, battery charging, and reverse battery protection.

MAJOR RATINGS AND CHARACTERISTICS			
SYMBOL	CHARACTERISTICS	VALUES	UNITS
$I_{F(AV)}$	Rectangular waveform	3.5	A
V_{RRM}		100	V
I_{FSM}	$t_p = 5 \mu s$ sine	440	A
V_F	3 Apk, $T_J = 125 \text{ °C}$	0.63	V
T_J		- 40 to 150	°C

VOLTAGE RATINGS			
PARAMETER	SYMBOL	VS-30WQ10FNPbF	UNITS
Maximum DC reverse voltage	V_R	100	V
Maximum working peak reverse voltage	V_{RWM}		

ABSOLUTE MAXIMUM RATINGS					
PARAMETER	SYMBOL	TEST CONDITIONS		VALUES	UNITS
Maximum average forward current See fig. 5	$I_{F(AV)}$	50 % duty cycle at $T_C = 135 \text{ °C}$, rectangular waveform		3.5	A
Maximum peak one cycle non-repetitive surge current See fig. 7	I_{FSM}	5 μs sine or 3 μs rect. pulse	Following any rated load condition and with rated V_{RRM} applied	440	
		10 ms sine or 6 ms rect. pulse		70	
Non-repetitive avalanche energy	E_{AS}	$T_J = 25 \text{ °C}$, $I_{AS} = 1 \text{ A}$, $L = 10 \text{ mH}$		5.0	mJ
Repetitive avalanche current	I_{AR}	Current decaying linearly to zero in 1 μs Frequency limited by T_J maximum $V_A = 1.5 \times V_R$ typical		0.5	A

ELECTRICAL SPECIFICATIONS					
PARAMETER	SYMBOL	TEST CONDITIONS		VALUES	UNITS
Maximum forward voltage drop See fig. 1	$V_{FM}^{(1)}$	3 A	$T_J = 25\text{ }^\circ\text{C}$	0.81	V
		6 A		0.96	
		3 A	$T_J = 125\text{ }^\circ\text{C}$	0.63	
		6 A		0.74	
Maximum reverse leakage current See fig. 2	$I_{RM}^{(1)}$	$T_J = 25\text{ }^\circ\text{C}$	$V_R = \text{Rated } V_R$	1	mA
		$T_J = 125\text{ }^\circ\text{C}$		4.9	
Threshold voltage	$V_{F(TO)}$	$T_J = T_J \text{ maximum}$		0.48	V
Forward slope resistance	r_t			30.89	m Ω
Typical junction capacitance	C_T	$V_R = 5 V_{DC}$ (test signal range 100 kHz to 1 MHz), 25 °C		92	pF
Typical series inductance	L_S	Measured lead to lead 5 mm from package body		5.0	nH
Maximum voltage rate of change	dV/dt	Rated V_R		10 000	V/ μ s

Note

(1) Pulse width < 300 μ s, duty cycle < 2 %

THERMAL - MECHANICAL SPECIFICATIONS					
PARAMETER	SYMBOL	TEST CONDITIONS		VALUES	UNITS
Maximum junction and storage temperature range	$T_J^{(1)}, T_{Stg}$			- 40 to 150	$^\circ\text{C}$
Maximum thermal resistance, junction to case	R_{thJC}	DC operation See fig. 4		4.7	$^\circ\text{C}/\text{W}$
Approximate weight				0.3	g
				0.01	oz.
Marking device		Case style D-PAK (similar to TO-252AA)		30WQ10FN	

Note

(1) $\frac{dP_{tot}}{dT_J} < \frac{1}{R_{thJA}}$ thermal runaway condition for a diode on its own heatsink

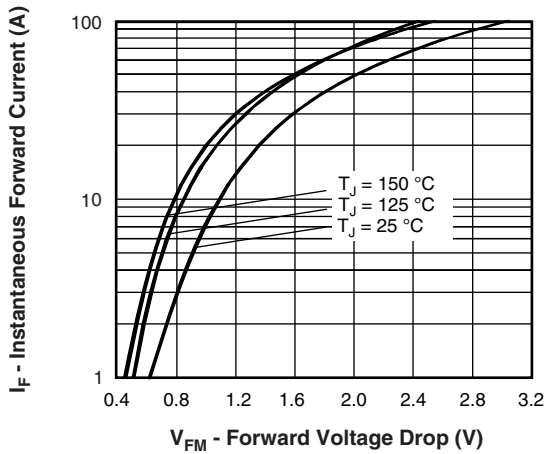


Fig. 1 - Maximum Forward Voltage Drop Characteristics

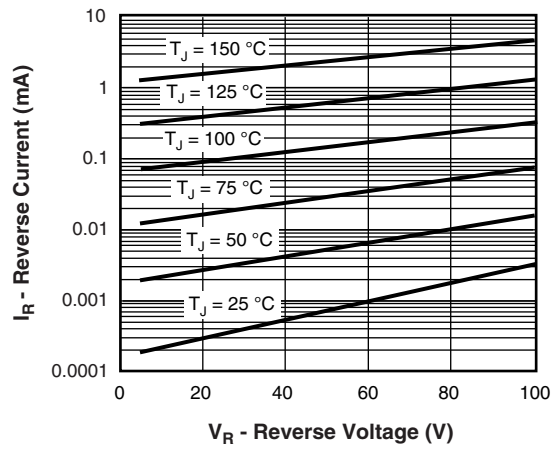


Fig. 2 - Typical Values of Reverse Current vs. Reverse Voltage

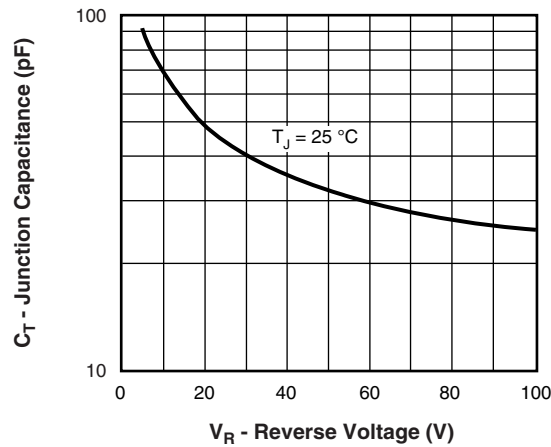


Fig. 3 - Typical Junction Capacitance vs. Reverse Voltage

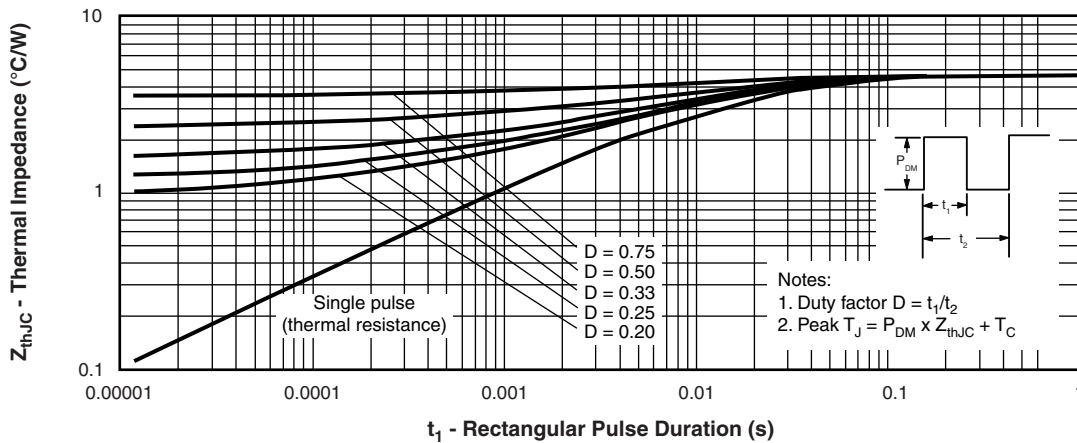


Fig. 4 - Maximum Thermal Impedance Z_{thJC} Characteristics

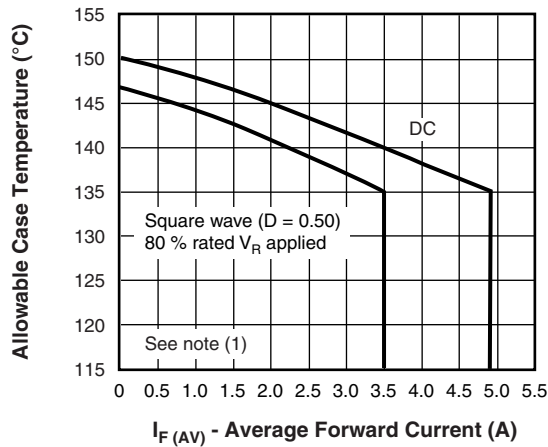


Fig. 5 - Maximum Allowable Case Temperature vs. Average Forward Current

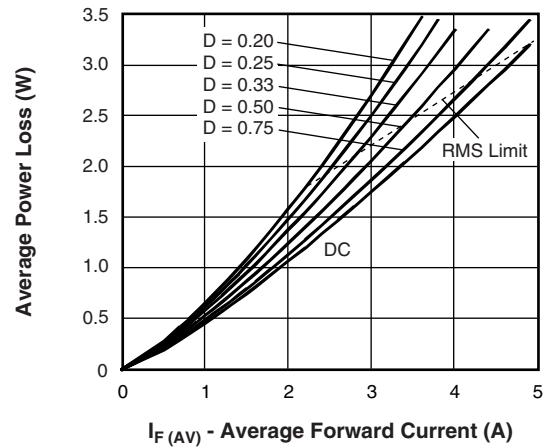


Fig. 6 - Forward Power Loss Characteristics

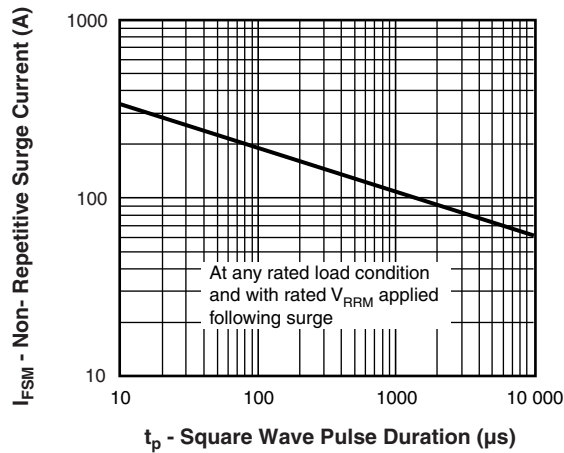


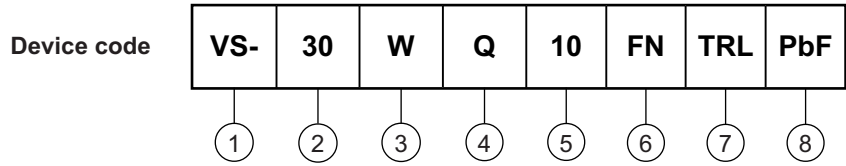
Fig. 7 - Maximum Non-Repetitive Surge Current

Note

- (1) Formula used: $T_C = T_J - (P_d + P_{d_{REV}}) \times R_{thJC}$;
 P_d = Forward power loss = $I_{F(AV)} \times V_{FM}$ at $(I_{F(AV)}/D)$ (see fig. 6);
 $P_{d_{REV}}$ = Inverse power loss = $V_{R1} \times I_R (1 - D)$; I_R at $V_{R1} = 80\%$ rated V_R



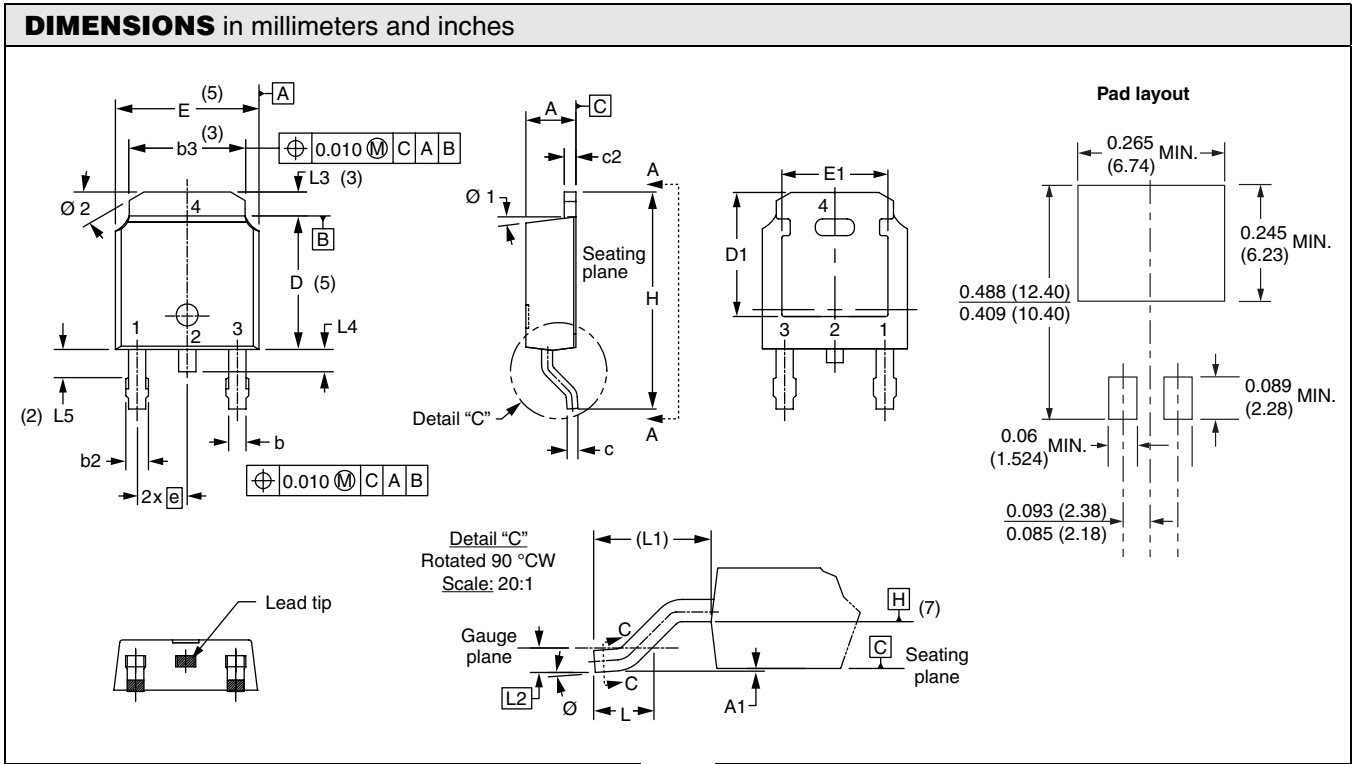
ORDERING INFORMATION TABLE



- 1** - Vishay Semiconductors product
- 2** - Current rating (3.5 A)
- 3** - Package identifier:
W = D-PAK
- 4** - Schottky "Q" series
- 5** - Voltage rating (10 = 100 V)
- 6** - FN = TO-252AA (D-PAK)
- 7** -
 - None = Tube (50 pieces)
 - TR = Tape and reel
 - TRL = Tape and reel (left oriented)
 - TRR = Tape and reel (right oriented)
- 8** - PbF = Lead (Pb)-free

LINKS TO RELATED DOCUMENTS	
Dimensions	www.vishay.com/doc?95016
Part marking information	www.vishay.com/doc?95059
Packaging information	www.vishay.com/doc?95033

D-PAK (TO-252AA)



SYMBOL	MILLIMETERS		INCHES		NOTES
	MIN.	MAX.	MIN.	MAX.	
A	2.18	2.39	0.086	0.094	
A1	-	0.13	-	0.005	
b	0.64	0.89	0.025	0.035	
b2	0.76	1.14	0.030	0.045	
b3	4.95	5.46	0.195	0.215	3
c	0.46	0.61	0.018	0.024	
c2	0.46	0.89	0.018	0.035	
D	5.97	6.22	0.235	0.245	5
D1	5.21	-	0.205	-	3
E	6.35	6.73	0.250	0.265	5
E1	4.32	-	0.170	-	3

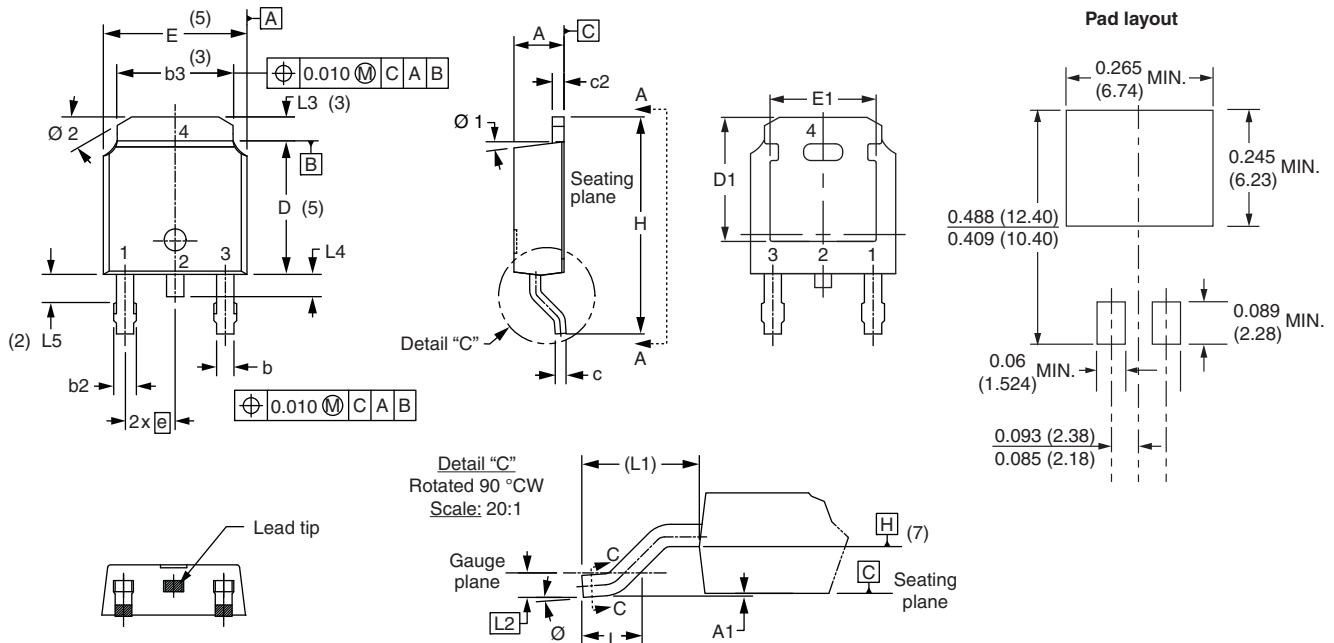
SYMBOL	MILLIMETERS		INCHES		NOTES
	MIN.	MAX.	MIN.	MAX.	
e	2.29 BSC		0.090 BSC		
H	9.40	10.41	0.370	0.410	
L	1.40	1.78	0.055	0.070	
L1	2.74 BSC		0.108 REF.		
L2	0.51 BSC		0.020 BSC		
L3	0.89	1.27	0.035	0.050	3
L4	-	1.02	-	0.040	
L5	1.14	1.52	0.045	0.060	2
Ø	0°	10°	0°	10°	
Ø1	0°	15°	0°	15°	
Ø2	25°	35°	25°	35°	

Notes

- (1) Dimensioning and tolerancing as per ASME Y14.5M-1994
- (2) Lead dimension uncontrolled in L5
- (3) Dimension D1, E1, L3 and b3 establish a minimum mounting surface for thermal pad
- (4) Section C - C dimension apply to the flat section of the lead between 0.13 and 0.25 mm (0.005 and 0.10") from the lead tip
- (5) Dimension D, and E do not include mold flash. Mold flash shall not exceed 0.127 mm (0.005") per side. These dimensions are measured at the outermost extremes of the plastic body
- (6) Dimension b1 and c1 applied to base metal only
- (7) Datum A and B to be determined at datum plane H
- (8) Outline conforms to JEDEC outline TO-252AA

D-PAK (TO-252AA)

DIMENSIONS in millimeters and inches



SYMBOL	MILLIMETERS		INCHES		NOTES	SYMBOL	MILLIMETERS		INCHES		NOTES
	MIN.	MAX.	MIN.	MAX.			MIN.	MAX.	MIN.	MAX.	
A	2.18	2.39	0.086	0.094		e	2.29 BSC		0.090 BSC		
A1	-	0.13	-	0.005		H	9.40	10.41	0.370	0.410	
b	0.64	0.89	0.025	0.035		L	1.40	1.78	0.055	0.070	
b2	0.76	1.14	0.030	0.045		L1	2.74 BSC		0.108 REF.		
b3	4.95	5.46	0.195	0.215	3	L2	0.51 BSC		0.020 BSC		
c	0.46	0.61	0.018	0.024		L3	0.89	1.27	0.035	0.050	3
c2	0.46	0.89	0.018	0.035		L4	-	1.02	-	0.040	
D	5.97	6.22	0.235	0.245	5	L5	1.14	1.52	0.045	0.060	2
D1	5.21	-	0.205	-	3	Ø	0°	10°	0°	10°	
E	6.35	6.73	0.250	0.265	5	Ø1	0°	15°	0°	15°	
E1	4.32	-	0.170	-	3	Ø2	25°	35°	25°	35°	

Notes

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- (6) Dimension b1 and c1 applied to base metal only
- (7) Datum A and B to be determined at datum plane H
- (8) Outline conforms to JEDEC outline TO-252AA



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